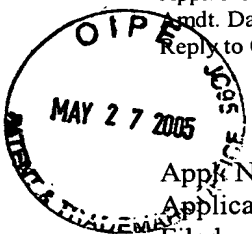


IFW

Appl. No. 10/762,015
Amtd. Dated May 25, 2005
Reply to Office action of April 4, 2005



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Appl. No. : 10/762,015
Applicant : Kiyoshi Arita
Filed : January 21, 2004
Title : METHOD OF MANUFACTURING SEMICONDUCTOR DEVICE
AND CUTTING APPARATUS FOR CUTTING SEMICONDUCTOR
WAFER

Conf. No. : 4497
TC/A.U. : 2812
Examiner : Scott B. Geyer

Customer No. : 000,116
Docket No. : 36395

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

AMENDMENT "A"

Sir:

This amendment is filed in response to the Office action dated April 4, 2005 (Paper No. 0305).

The two month period for responding to the Office action expires on June 4, 2005.

Please amend the above-identified application in the following manner.

Amendments to the Specification begin on page 2 of this paper, and include one replacement sheet.

Amendments to the Claims are reflected in the listing of claims which begins on page 8 of this paper.

Remarks/Arguments begin on page 13 of this paper.

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on the date indicated below.

Tomoko Ishihara
Name of Agent for Applicant(s)

5/25/2005
Signature of Agent/Date